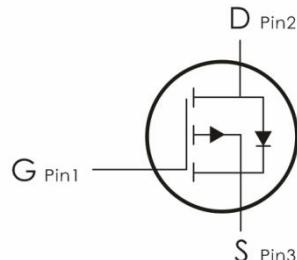
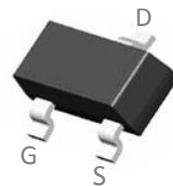


Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-20V, I_D=-2A, R_{DS(ON)}<125m\Omega @ V_{GS}=-4.5V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current- $T_A=25^\circ C$	-2	A
	Continuous Drain Current- $T_A=100^\circ C$	-1.3	A
I_{DM}	Pulse Drain Current Tested ¹	-8	A
P_D	Power Dissipation- $T_A=25^\circ C$	0.8	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{JA}	Thermal Resistance,Junction to Ambient	156	$^\circ C/W$

Package Marking and Ordering Information:

Part No.	Marking	Package
DO2301E-Q	A1SHB:	SOT-23

Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250 \mu\text{A}$	-20	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-20\text{V}$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_D=250 \mu\text{A}$	-0.4	-0.7	-1	V
$R_{\text{DS(ON)}}$	Drain-Source On Resistance ²	$V_{\text{GS}}=-4.5\text{V}, I_D=-2\text{A}$	---	95	125	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_D=-1\text{A}$	---	135	190	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	150	---	pF
C_{oss}	Output Capacitance		---	34	---	
C_{rss}	Reverse Transfer Capacitance		---	24	---	
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}}=-10\text{V}, R_{\text{GEN}}=3 \Omega, V_{\text{GS}}=-4.5\text{V}$	---	9	---	ns
t_r	Rise Time		---	29	---	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		---	62	---	ns
t_f	Fall Time		---	49	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DS}}=-10\text{V}, I_D=-2\text{A}$	---	2.1	---	nC
Q_{gs}	Gate-Source Charge		---	0.4	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	0.4	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Forward Voltage ¹	$V_{\text{GS}}=0\text{V}, I_S=-2\text{A}$	---	---	-1.2	V
I_D	Continuous Drain Current	$V_G=V_D=0\text{V}$	---	---	-2	A
I_{DM}	Pulse Drain Current Tested	$V_G=V_D=0\text{V}$	---	---	-8	A

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Characteristics:

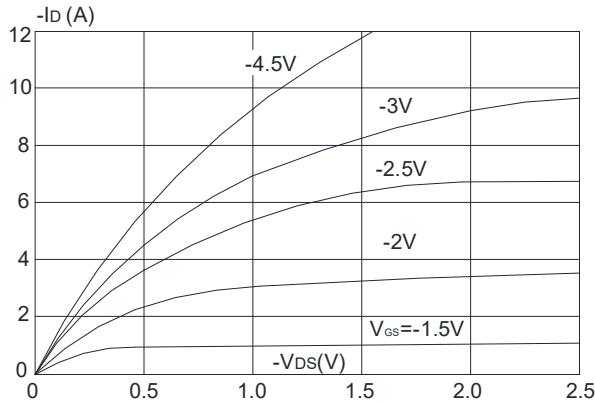


Figure 1: Output Characteristics

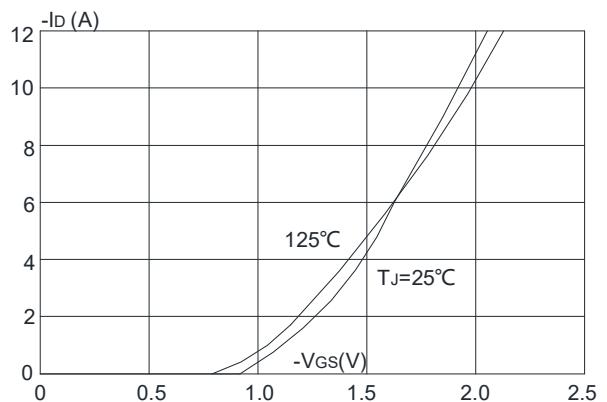


Figure 2: Typical Transfer Characteristics

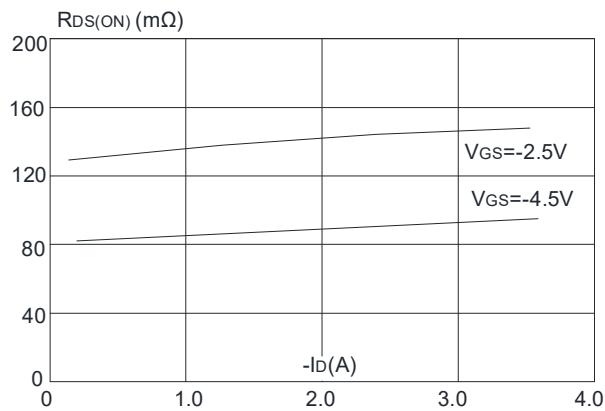


Figure 3: On-resistance vs. Drain Current

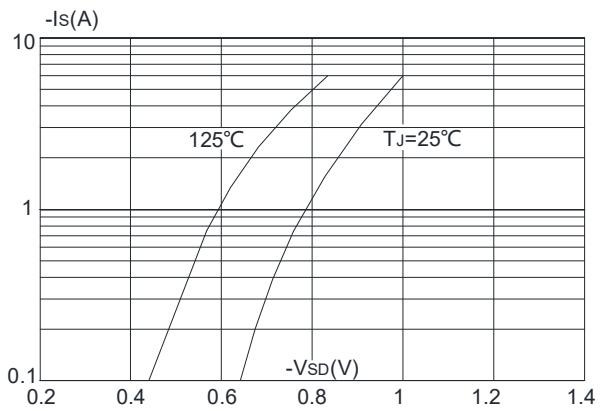


Figure 4: Body Diode Characteristics

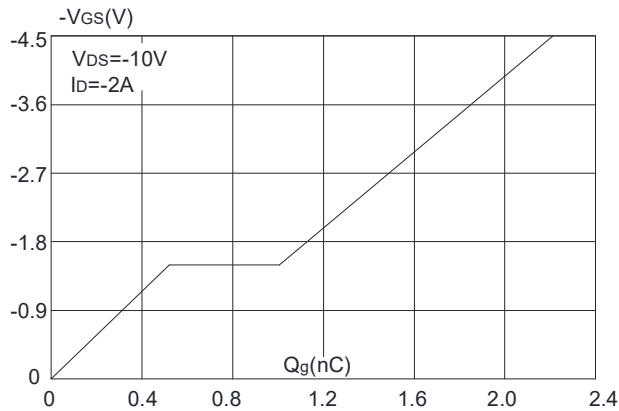


Figure 5: Gate Charge Characteristics

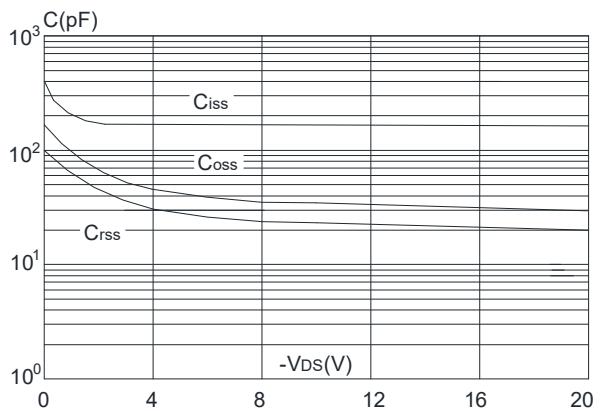


Figure 6: Capacitance Characteristics

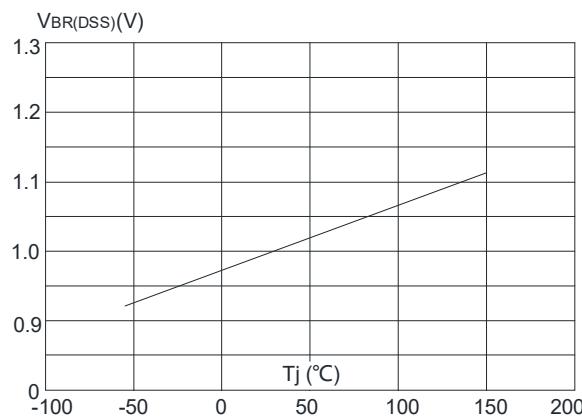


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

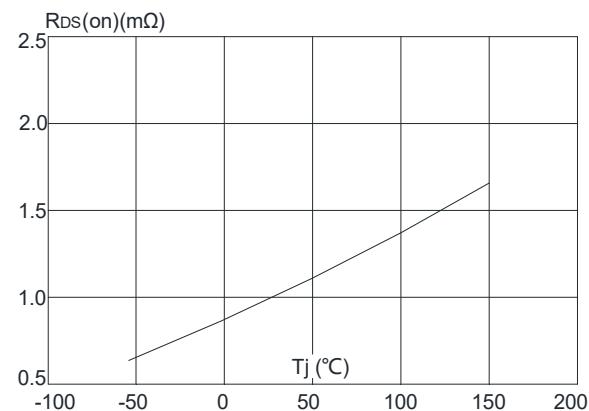


Figure 8: Normalized on Resistance vs. Junction Temperature

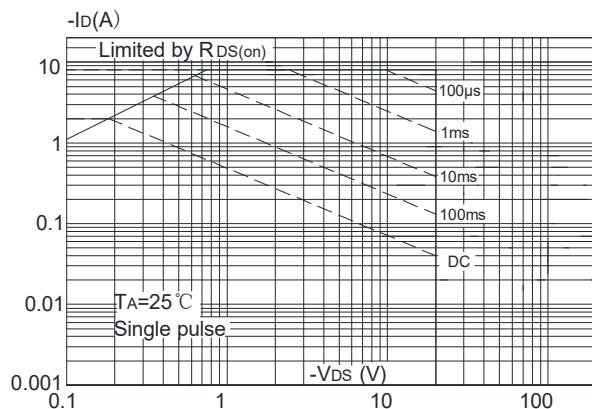


Figure 9: Maximum Safe Operating Area

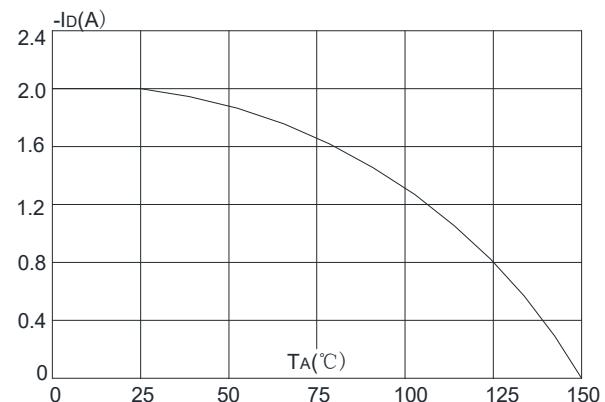


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

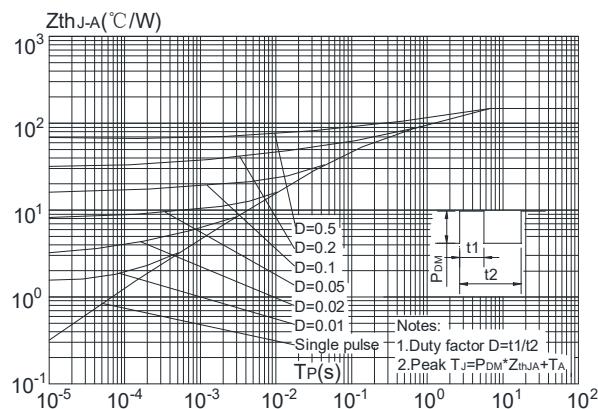


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient